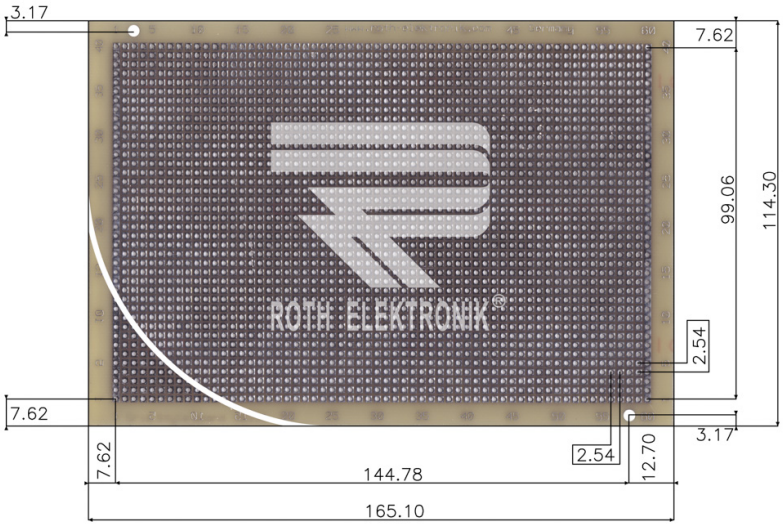

RE233-LF

- Epoxy fibre-glass FR4 1.60 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Hot air leveling (HAL-leadfree)
- Hole spacing 2.54 x 2.54 mm
- 40 x 60 tracks of bored holes
- 40 x 56 soldering pads 2.00 x 2.00 mm
- Hole diameter 1.02 mm (0.40")
- 2 potential strips
- Max. working temperature 150 °C (302 °F)
- Size 114.30 mm x 165.10 mm (4.5" x 6.5")

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